

Chemical content NCR421U

Type number	Package	Package description	Total product weight
NCR421U	SOT457	SC-74	12.49813 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
934070297115	5	1	260	30 s	1	235	20 s	3	D-22529 HAMBURG, Germany; Seremban, Malaysia	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.03080	77.00000	0.24644
		Polymer	Resin system	Proprietary	0.00920	23.00000
			subTotal		0.04000	100.00000
Die	Doped silicon	Silicon (Si)	7440-21-3	0.20000	100.00000	1.60024
			subTotal	0.20000	100.00000	1.60024
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	5.17408	97.80870	41.39884
		Iron (Fe)	7439-89-6	0.11262	2.12900	0.90113
	Pure metal layer	Copper (Cu)	7440-50-8	0.00170	0.03220	0.01363
		Silver (Ag)	7440-22-4	0.00159	0.03010	0.01274
		subTotal		5.29000	100.00000	42.32634
Mould Compound	Filler	Silica fused	60676-86-0	4.66470	71.00000	37.32318
	Pigment	Carbon black	1333-86-4	0.01971	0.30000	0.15770
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	1.29429	19.70000	10.35587
		Phenolic resin	Proprietary	0.59130	9.00000	4.73111
		subTotal		6.57000	100.00000	52.56786
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00001	0.00300	0.00009
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00003
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00003
		Lead (Pb)	7439-92-1	0.00002	0.00500	0.00015
	Tin solder	Tin (Sn)	7440-31-5	0.37996	99.99000	3.04015
		subTotal		0.38000	100.00000	3.04045
Wire	Pure metal	Gold (Au)	7440-57-5	0.01813	100.00000	0.14506
			subTotal	0.01813	100.00000	0.14506

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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